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February 1998 Revised June 2005

74VHC161284 IEEE 1284 Transceiver

General Description

The VHC161284 contains eight bidirectional data buffers and eleven control/status buffers to implement a full IEEE 1284 compliant interface. The device supports the IEEE 1284 standard and is intended to be used in Extended Capabilities Port mode (ECP). The pinout allows for easy connection from the Peripheral (A-side) to the Host (cable side).

Outputs on the cable side can be configured to be either open drain or high drive (\pm 14 mA). The pull-up and pull-down series termination resistance of these outputs on the cable side is optimized to drive an external cable. In addition, all inputs (except HLH) and outputs on the cable side contain internal pull-up resistors connected to the V_{CC} supply to provide proper termination and pull-ups for open drain mode

Outputs on the Peripheral side are standard LOW-drive CMOS outputs. The DIR input controls data flow on the $A_1\!\!-\!A_8/B_1\!\!-\!B_8$ transceiver pins.

Features

- Supports IEEE 1284 Level 1 and Level 2 signaling standards for bidirectional parallel communications between personal computers and printing peripherals
- Replaces the function of two (2) 74ACT1284 devices
- All inputs have hysteresis to provide noise margin
- B and Y output resistance optimized to drive external cable
- B and Y outputs in high impedance mode during power down
- Inputs and outputs on cable side have internal pull-up resistors
- Flow-through pin configuration allows easy interface between the Peripheral and Host

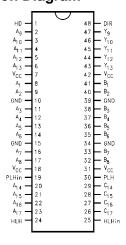
Ordering Code:

Ordering Number	Package Number	Package Description
74VHC161284MEA	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
74VHC161284MTD	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Surface mount packages are also available on Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol

Connection Diagram



Pin Descriptions

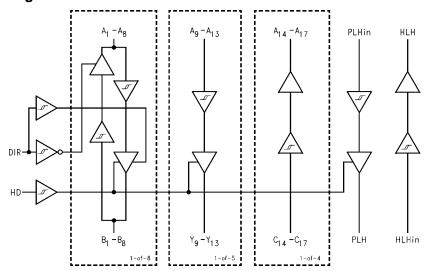
Pin Names	Description
HD	HIGH Drive Enable Input (Active HIGH)
DIR	Direction Control Input
A ₁ -A ₈	Inputs or Outputs
B ₁ -B ₈	Inputs or Outputs
A ₉ -A ₁₃	Inputs
Y ₉ -Y ₁₃	Outputs
A ₁₄ -A ₁₇	Outputs
C ₁₄ –C ₁₇	Inputs
PLH _{IN}	Peripheral Logic HIGH Input
PLH	Peripheral Logic HIGH Output
HLH _{IN}	Host Logic HIGH Input
HLH	Host Logic HIGH Output

Truth Table

Inp	outs	Outputs		
DIR	HD	Outputs		
L	L	B ₁ -B ₈ Data to A ₁ -A ₈ , and		
		$A_9 - A_{13}$ Data to $Y_9 - Y_{13}$ (Note 1)		
		C ₁₄ –C ₁₇ Data to A ₁₄ –A ₁₇		
		PLH Open Drain Mode		
L	Н	B ₁ -B ₈ Data to A ₁ -A ₈ , and		
		A_9 – A_{13} Data to Y_9 – Y_{13}		
		C ₁₄ –C ₁₇ Data to A ₁₄ –A ₁₇		
Н	L	A ₁ -A ₈ Data to B ₁ -B ₈ (Note 2)		
		A ₉ -A ₁₃ Data to Y ₉ -Y ₁₃ (Note 1)		
		C ₁₄ –C ₁₇ Data to A ₁₄ –A ₁₇		
		PLH Open Drain Mode		
Н	Н	A ₁ –A ₈ Data to B ₁ –B ₈		
		A_9 – A_{13} Data to Y_9 – Y_{13}		
		C ₁₄ -C ₁₇ Data to A ₁₄ -A ₁₇		

Note 1: Y₉–Y₁₃ Open Drain Outputs Note 2: B₁–B₈ Open Drain Outputs

Logic Diagram



Absolute Maximum Ratings(Note 3) Recommended Operating Conditions

Supply Voltage

 $\label{eq:VCC} V_{CC} & -0.5 \text{V to} + 7.0 \text{V} \\ \text{Input Voltage (V_1) (Note 4)}$

 $\begin{array}{lll} & & & & & & & & & & & & & & & & \\ & A_1-A_{13}, \ PLH_{IN}, \ DIR, \ HD & & & & & & & & & & \\ B_1-B_8, \ C_{14}-C_{17}, \ HLH_{IN} & & & & & & & & & \\ B_1-B_8, \ C_{14}-C_{17}, \ HLH_{IN} & & & & & & & & \\ & & & & & & & & & \\ \end{array} \qquad \begin{array}{ll} & -0.5V \ to \ V_{CC} + 0.5V \\ & -0.5V \ to + 5.5V \ (DC) \\ & -2.0V \ to + 7.0V \ ^* \end{array}$

*40 ns Transient

Output Voltage (V_O)

DC Output Current (I_O)

Input Diode Current (I_{IK}) (Note 4)

DIR, HD, A₉-A₁₃,

PLH, HLH, C₁₄–C₁₇ –20 mA

Output Diode Current (I_{OK})

A₁-A₈, A₁₄-A₁₇, HLH ±50 mA

 B_1-B_8 , Y_9-Y_{13} , PLH -50 mA

DC Continuous $V_{\mbox{\footnotesize CC}}$ or

Ground Current $\pm 200 \text{ mA}$

Storage Temperature -65°C to + 150°C

ESD (HBM) Last Passing

Voltage 2000V

Supply Voltage

 $\begin{array}{c} \text{V}_{\text{CC}} & \text{4.5V to 5.5V} \\ \text{DC Input Voltage (V_I)} & \text{0V to V}_{\text{CC}} \\ \text{Open Drain Voltage (V}_{\text{O}}) & \text{0V to 5.5V} \\ \text{Operating Temperature (T}_{\text{A}}) & -40^{\circ}\text{C to} + 85^{\circ}\text{C} \\ \end{array}$

*40 ns Transient

Note 3: Absolute Maximum continuos ratings are those values beyond which damage to the device may occur. Exposure to these indicated may adversely affect device reliability. Functional operation under absolute maximum rated conditions is not implied.

Note 4: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

Symbol	Parameter		(v)	T _A = -40°C to +85°C Guaranteed Limits	Units	Conditions
V _{IK}	Input Clamp Diode Voltage		3.0	-1.2	V	I _I = -18 mA
V _{IH}	Minimum HIGH Level Input Voltage	A _n , PLH _{IN} , DIR, HD	4.5 – 5.5	0.7 V _{CC}		
		B _n	4.5 – 5.5	2.0	v	
		C _n	4.5 – 5.5	2.3	'	
		HLH _{IN}	4.5 – 5.5	2.6		
V _{IL}	Maximum LOW Level Input Voltage	A _n , PLH _{IN} , DIR, HD	4.5 – 5.5	0.3 V _{CC}		
		B _n	4.5 – 5.5	0.8	v	
		C _n	4.5 – 5.5	0.8	V	
		HLH _{IN}	4.5 – 5.5	1.6		
ΔVΤ	Minimum Input Hysteresis	A _n , PLH _{IN} , DIR, HD	4.5 – 5.5	0.4		V _T + –V _T
		B _n	4.5 – 5.5	0.4	V	$V_T^+ - V_T^-$
		C _n	5.0	0.8		V _T + –V _T –
		HLH _{IN}	5.0	0.3		V _T + –V _T –
V _{OH}	Minimum HIGH Level Output Voltage	A _n , HLH	4.5	4.4		$I_{OH} = -50 \mu A$
			4.5	3.8	V	$I_{OH} = -8 \text{ mA}$
		B _n , Y _n	4.5	3.73		I _{OH} = -14 mA
		PLH	4.5	4.45		I _{OH} = -500 μA

DC Electrical Characteristics (Continued)

Symbol	Parameter			T _A = -40°C to +85°C Guaranteed Limits	Units	Conditions
V _{OL}	Maximum LOW Level Output Voltage	A _n , HLH	4.5	0.1		I _{OL} = 50 μA
			4.5	0.44	V	$I_{OL} = 8 \text{ mA}$
		B _n , Y _n	4.5	0.77	v	I _{OL} = 14 mA
		PLH	4.5	0.7		$I_{OL} = 84 \text{ mA}$
RD	Maximum Output Impedance	B ₁ -B ₈ , Y ₉ -Y ₁₃	5.0	55	Ω	(Note 5)(Note 6)
	Minimum Output Impedance	B ₁ -B ₈ , Y ₉ -Y ₁₃	5.0	35	Ω	(Note 5)(Note 6)
RP	Maximum Pull-Up Resistance	B ₁ -B ₈ , Y ₉ -Y ₁₃ , C ₁₄ -C ₁₇	5.0	1650	Ω	
	Minimum Pull-Up Resistance	B ₁ -B ₈ , Y ₉ -Y ₁₃ , C ₁₄ -C ₁₇	5.0	1150	Ω	
I _{IH}	Maximum Input Current in HIGH State	A ₉ –A ₁₃ , PLH _{IN} , HD, DIR, HLH _{IN}	5.5	1.0	цΑ	$V_I = 5.5V$
		C ₁₄ -C ₁₇	5.5	100	μΑ	$V_I = 5.5V$
I _{IL}	Maximum Input Current in LOW State	A ₉ -A ₁₃ , PLH _{IN} , HD, DIR, HLH _{IN}	5.5	-1.0	μА	$V_I = 0.0V$
		C ₁₄ -C ₁₇	5.5	-5.0	mA	$V_I = 0.0V$
I _{OZH}	Maximum Output Disable Current	A ₁ —A ₈	5.5	20	цΑ	V _O = 5.5V
	(HIGH)	B ₁ –B ₈	5.5	100	μΛ	V _O = 5.5V
I _{OZL}	Maximum Output Disable Current	A ₁ —A ₈	5.5	-20	μА	$V_0 = 0.0V$
	(LOW)	B ₁ –B ₈	5.5	-5.0	mA	
I _{OFF}	Power Down Output Leakage	B ₁ -B ₈ , Y ₉ -Y ₁₃ , PLH	0.0	100	μА	V _O = 5.5V
I _{OFF}	Power Down Input Leakage	C ₁₄ –C ₁₇ , HLH _{IN}	0.0	100	μА	$V_I = 5.5V$
I _{OFF} - I _{CC}	Power Down Leakage to V _{CC}		0.0	250	μА	(Note 7)
I _{CC}	Maximum Supply Current		5.5	70	mA	$V_I = V_{CC}$ or GND

Note 5: Output impedance is measured with the output active LOW and active HIGH (HD = HIGH).

Note 7: Power-down leakage to V_{CC} is tested by simultaneously forcing all pins on the cable-side (B₁–B₈, Y_9 – Y_{13} , PLH, C_{14} – C_{17} and HLH $_{IN}$ to 5.5V and measuring the resulting I_{CC} .

Note 6: This parameter is guaranteed but not tested, characterized only.

AC Electrical Characteristics

		T _A = -40°	C to +85°C	Units	Figure Number
Symbol	Parameter	$V_{CC}=4.$	5V – 5.5V		
		Min	Max		
t _{PHL}	A ₁ -A ₈ to B ₁ -B ₈	2.0	30.0	ns	Figure 1
t _{PLH}	A ₁ -A ₈ to B ₁ -B ₈	2.0	30.0	ns	Figure 2
t _{PHL}	B ₁ -B ₈ to A ₁ -A ₈	2.0	30.0	ns	Figure 3
t _{PLH}	B ₁ -B ₈ to A ₁ -A ₈	2.0	30.0	ns	Figure 3
t _{PHL}	A ₉ -A ₁₃ to Y ₉ -Y ₁₃	2.0	30.0	ns	Figure 1
t _{PLH}	A ₉ -A ₁₃ to Y ₉ -Y ₁₃	2.0	30.0	ns	Figure 2
t _{PHL}	C ₁₄ -C ₁₇ to A ₁₄ -A ₁₇	2.0	30.0	ns	Figure 3
t _{PLH}	C ₁₄ -C ₁₇ to A ₁₄ -A ₁₇	2.0	30.0	ns	Figure 3
t _{SKEW}	LH-LH or HL-HL		6.0	ns	(Note 9)
t _{PHL}	PLH _{IN} to PLH	2.0	30.0	ns	Figure 1
t _{PLH}	PLH _{IN} to PLH	2.0	30.0	ns	Figure 2
t _{PHL}	HLH _{IN} to HLH	2.0	30.0	ns	Figure 3
t _{PLH}	HLH _{IN} to HLH	2.0	30.0	ns	Figure 3
t _{PHZ}	Output Disable Time	2.0	18.0		Figure 7
t_{PLZ}	DIR to A ₁ -A ₈	2.0	18.0	ns	
t _{PZH}	Output Enable Time	2.0	25.0	no	Figure 8
t _{PZL}	DIR to A ₁ -A ₈	2.0	25.0	ns	
t _{PHZ}	Output Disable Time	2.0	25.0	20	Figure 9
t _{PLZ}	DIR to B ₁ -B ₈	2.0	25.0	ns	
t _{pEN}	Output Enable Time	2.0	00.0		Figure 2
	HD to B ₁ –B ₈ , Y ₉ –Y ₁₃	2.0	28.0	ns	
t _{pDis}	Output Disable Time	2.0	20.0		Figure 2
·	HD to B ₁ –B ₈ , Y ₉ –Y ₁₃	2.0	28.0	ns	Figure 2
t _{pEn} -t _{pDis}	Output Enable-Output Disable		20.0	ns	
t _{SLEW}	Output Slew Rate				
t _{PLH}	B ₁ -B ₈ , Y ₉ -Y ₁₃	0.05	0.40	V/ns	Figure 5
t _{PHL}		0.05	0.40	V/IIS	Figure 4
t _r , t _f	t _{RISE} and t _{FALL}		120	†	Figure 6
	B ₁ -B ₈ , Y ₉ -Y ₁₃ (Note 8)		120	ns	(Note 10)

Note 8: Open Drain

 $\textbf{Note 9: } t_{\text{SKEW}} \text{ is measured for common edge output transitions and compares the measured propagation delay for a given path type.} \\$

(i) $A_1 \! - \! A_8$ to $B_1 \! - \! B_8,\, A_9 \! - \! Y_{13}$ to $Y_9 \! - \! Y_{13}$

(ii) B₁-B₈ to A₁-A₈

(iii) C_{14} – C_{17} to A_{14} – A_{17}

Note 10: This parameter is guaranteed but not tested, characterized only.

Capacitance (Note 11)

Symbol	Parameter	Тур	Units	Conditions
C _{IN}	Input Capacitance	5	pF	$V_{CC} = 0.0V$ (HD, DIR, A_9 — A_{13} , C_{14} — C_{17} , PLH _{IN} and HLH _{IN})
C _{I/O}	I/O Pin Capacitance	12	pF	$V_{CC} = 3.3V$

Note 11: Capacitance is measured at frequency = 1 MHz.

AC Loading and Waveforms Pulse Generator for all pulses: Rate ≤ 1.0 MHz; Z_O $\leq 50\Omega$; t_f ≤ 2.5 ns, t_f ≤ 2.5 ns.

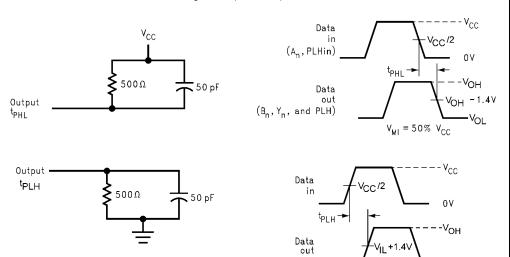


FIGURE 1. Part A to B and A to Y Propagation Delay Load and Waveforms

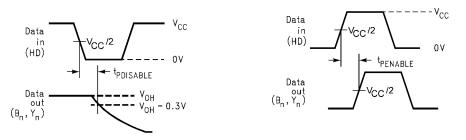


FIGURE 2. Port A to B and a to Y Output Waveforms

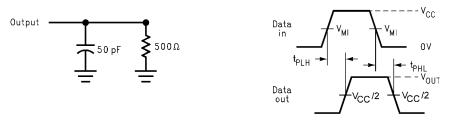
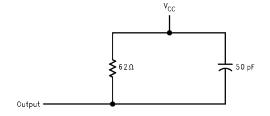


FIGURE 3. Port B to A, C to A and HLHin to HLH Propagation Delay Waveforms

AC Loading and Waveforms (Continued)



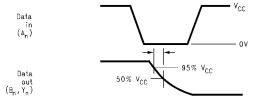


FIGURE 4. Port A to B and A to Y HL Slew Test Load and Waveforms

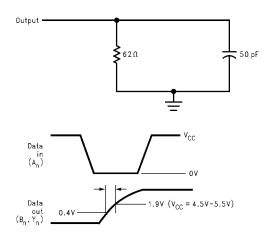


FIGURE 5. Part A to b and A to Y LH Slew Test Load and Waveforms

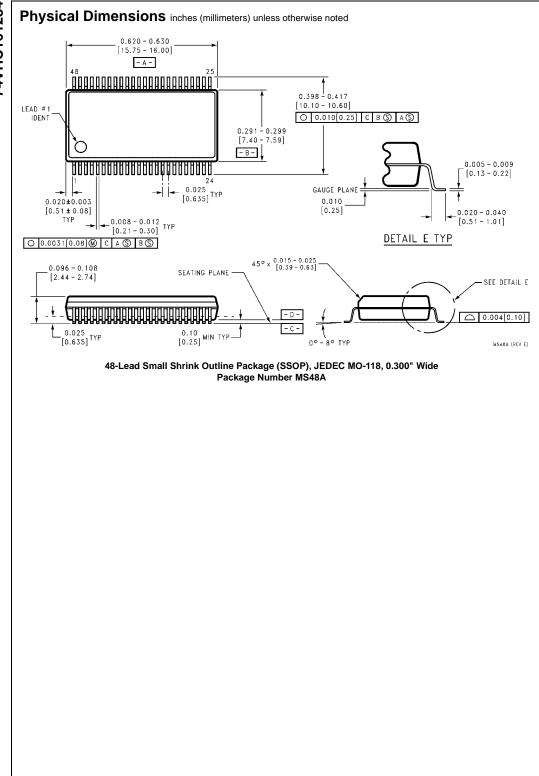


t_f = Output Fall Time, Open Drain

FIGURE 6. t_{RISE} and t_{FALL} Test Load and Waveforms for Open Drain Outputs A_1-A_8 to B_1-B_8 , A_9-A_{13} to Y_9-Y_{13}

AC Loading and Waveforms (Continued) V_{CC} x2 for l_{PLZ} GND for t_{PHZ} **\$** 500Ω **\$** 500Ω 50 pF V_{OH} VOH-0.3V V_{OL}+0.3V FIGURE 7. t_{PHZ} and t_{PLZ} Test Load and Waveforms, DIR to A_1 - A_8 V_{CC} ×2 for t_{PZL} GND for t_{PZH} 5000 **≸**500Ω 50 aF DIR -- ΨZH 1.45V when $V_{00} = 4.5V$ 1.75V when $V_{00} = 5.5V$ 50% of Transition 50% of fransition 3.25V when $V_{OC} = 4.5V$ 3.95V when $V_{OC} = 5.5V$ FIGURE 8. $t_{\mbox{\scriptsize PZH}}$ and $t_{\mbox{\scriptsize PZL}}$ Test Load and Waveforms, DIR to $\mbox{A}_{\mbox{\scriptsize 1}}\mbox{-}\mbox{A}_{\mbox{\scriptsize 8}}$

AC Loading and Waveforms (Continued) **≸** 500ก \$ 500Ω FIGURE 9. t_{PHZ} and t_{PLZ} Test Load and Waveforms, DIR to B_1-B_8



Physical Dimensions inches (millimeters) unless otherwise noted (Continued) -12.50±0.10 0.40 TYP -B-99. 8.10 4.05 O.2 C B A ALL LEAD TIPS PIN #1 IDENT 0.50 LAND PATTERN RECOMMENDATION □ 0.1 C SEE DETAIL A 0.90+0.15 0.09-0.20-0.10±0.05 0.50 0.17-0.27 **♦** 0.13**®** A B\$ C\$ 12.00' TOP & BOTTOM DIMENSIONS ARE IN MILLIMETERS R0.16 GAGE PLANE 0.25 NOTES: A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ED, DATE 4/97. B. DIMENSIONS ARE IN MILLIMETERS. SEATING PLANE 0.60±0.10 — 1.DD C, DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. DETAIL A MTD48REVC

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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